KYOCERA KE-1100A-S3

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Molding Compounds for Area Array Packages (BGA, CSP etc.)
Special Epoxy Molding Compounds Optimizing Warpage and Applicable to Fine Pitch Wire for BGA Package
Strong Points
Less Warpage in All Types of Area Array Packages due to High Tg Characteristic.
Applicable to Fine Pitch Wire Bonding with Good Wire Sweep Performance.
Achieve High Yield after Molding due to Excellent Moldability that allows its application to MAP.
Application
Standard P-BGA, HS-BGA and LGA Package.
Multi Chip Module (Stacked or Side by Side Layout)
IC Card, Memory Card etc.
Low Alpha Ray Type: KE-2100A-S3

General Information		
Features	Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	**Nominal Value**	**Unit**
Specific Gravity	1.90	g/cm³
Spiral Flow	190	cm
Solution Viscosity	6000	mPa·s
Mechanical	**Nominal Value**	**Unit**
Flexural Modulus	15000	MPa
Flexural Strength	130	MPa
Thermal	**Nominal Value**	**Unit**
Glass Transition Temperature	200	°C
CLTE - Flow		
-- [1]	1.4E-5	cm/cm/°C
-- [2]	4.9E-5	cm/cm/°C

NOTE	
1.	Alpha 1
2.	Alpha 2

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WECHAT